

11-07-2002



Form PTO-1595 (Rev. 03/01)

RE

U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

OMB No. 0651-0027 (exp. 5/31/2002)

102275091

Tab settings

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

LEE CHOON KUAN
CHONG CHIN HUI
LEE WANG LAI

10-28-02

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: MICRON TECHNOLOGY, INC.

Internal Address:

Legal Department, M/S 525

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83706

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: September 26, 2002

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 9/26/02

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Stephen A. Gratton

Internal Address:

THE LAW OFFICE OF STEPHEN A. GRATTON

Street Address: 2764 South Braun Way

City: Lakewood State: CO Zip: 80228

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

07-1857

DO NOT USE THIS SPACE

9. Signature.

Stephen A. Gratton, #28,418

Name of Person Signing

Signature

10/29/2002

Date

Total number of pages including cover sheet, attachments, and documents: 4

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

11/06/2002 TBI AZ1 00000116 071857 10282405

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11002 U.S. P.T.O. 10/29/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

LEE CHOON KUAN
CHONG CHIN HUI
LEE WANG LAI

Serial No.:

Filing Date: Concurrently Herewith

Title: SEMICONDUCTOR PACKAGE HAVING MULTI-LAYER
LEADFRAME AND METHOD OF FABRICATION

Docket No. 02-0580

ASSIGNMENT:

Enclosed for recording

Previously recorded

Date: _____

Reel: _____

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency, and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN, AND TRANSFER to Micron Technology, Inc. (the "Assignee"), a corporation of the State of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83706-9632, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which will be executed by the undersigned and is entitled: **SEMICONDUCTOR PACKAGE HAVING MULTI-LAYER LEADFRAME AND METHOD OF FABRICATION**; such application and all divisional, continuing, substitute, renewal, reissue, and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST, the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney, and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining, and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

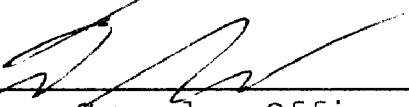
TO BE BINDING on the heirs, assigns, representatives, and successors of the undersigned and extend to the successors, assigns, and nominees of the Assignee.

(Signature) 
LEE CHOON KUAN

Date 26 SEP 2002

SINGAPORE)ss

BEFORE ME, this 26 SEP 2002 day of _____, 2001, personally appeared the above named individual(s), to me known to be the person(s) who is (are) described in and who executed the foregoing assignment instrument and acknowledged to me that he/she executed the same of his/her (their) own free will for the purpose therein expressed.


Notary or Consular Officer of the United States of America

My Commission Expires: _____



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

LEE CHOON KUAN
CHONG CHIN HUI
LEE WANG LAI

Serial No.:

Filing Date: Concurrently Herewith

Title: SEMICONDUCTOR PACKAGE HAVING MULTI-LAYER
LEADFRAME AND METHOD OF FABRICATION

Docket No. 02-0580

ASSIGNMENT:

Enclosed for recording

Previously recorded

Date: _____

Reel: _____

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency, and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN, AND TRANSFER to Micron Technology, Inc. (the "Assignee"), a corporation of the State of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83706-9632, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which will be executed by the undersigned and is entitled: **SEMICONDUCTOR PACKAGE HAVING MULTI-LAYER LEADFRAME AND METHOD OF FABRICATION**; such application and all divisional, continuing, substitute, renewal, reissue, and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST, the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney, and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining, and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives, and successors of the undersigned and extend to the successors, assigns, and nominees of the Assignee.

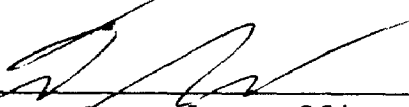
(Signature) 
LEE CHOON KUAN

Date 28 SEP 2002

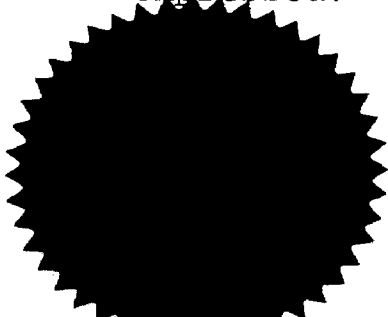
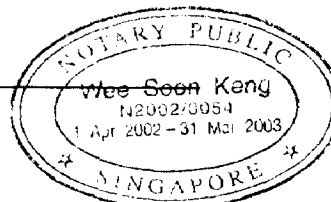
SINGAPORE

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BEFORE ME, this 28 day of SEP 2002, 2001, personally appeared the above named individual(s), to me known to be the person(s) who is (are) described in and who executed the foregoing assignment instrument and acknowledged to me that he/she executed the same of his/her (their) own free will for the purpose therein expressed.


Notary or Consular Officer of the United States of America

My Commission Expires: _____



MICRON TECHNOLOGY, INC.

2

Docket No. 02-0580